

REMARKS

Reconsideration of this Application is respectfully requested in light of the following remarks. Claims 1, 3-12 and 25 are now currently active in this application, of which claims 1, 6 and 9 are independent.

Entry of the Remarks is respectfully requested because it places the present application in condition for allowance, or in the alternative, better form for appeal. No new matters are believed to be added by Reply. Based on the following Remarks, Applicants respectfully request that the Examiner reconsider the outstanding objections and rejections and they be withdrawn.

A list of pending claims is attached herewith as **Appendix A**.

Rejections Under 35 U.S.C. §102

In the Office Action, claims 1, 3-5 and 12 have been rejected under 35 U.S.C. §102(e) for being anticipated by U. S. Patent No. 6,433,487 issued to Yamazaki, ("Yamazaki"). This rejection is respectfully traversed.

Claim 1 of the present Application recites an organic EL device, comprising: ... an organic EL substrate including a second insulating substrate, a transparent electrode, an organic EL layer and a metal electrode.

Yamazaki neither discloses nor suggests such features. The Examiner alleges that Figs. 1, 11 and 14 of Yamazaki show an organic EL substrate including a second insulating substrate, a transparent electrode 47, an organic EL layer 46 and a metal electrode 44. Applicants disagree with the Examiner's allegation.

As the Examiner admits, the referenced Figures of Yamazaki do not show a second insulating substrate. Yamazaki simply shows a TFT array substrate with a pixel electrode 43, a

cathode 44, an EL layer 46, an anode 47 and a second passivation layer 48. Therefore, Yamazaki device does not disclose an organic EL substrate including a second insulating substrate, a transparent electrode, an organic EL layer and a metal electrode, as recited in claim 1 of the present Application. It is inherently impossible for the Yamazaki device to have such an organic EL substrate, because the pixel electrode 43, the cathode 44, the EL layer 46, the anode 47 and the second passivation layer 48 are all formed on the TFT array substrate sequentially after forming TFTs on the substrate. (See col. 6, line 1 through col. 8, line 20 of Yamazaki)

Likewise, claims 3-5 and 12 that are dependent from claim 1 are also patentable over Yamazaki. The Examiner rejected claims 3-5 and 12 for other various reasons. However, as discussed previously, those claim are dependent from claim 1 that patentable over Yamazaki and the Examiner failed to produce any further reference.

Accordingly, Applicants respectfully request that the rejection over claims 1, 3-5 and 12 be withdrawn and pass those claims to allowance.

In the Office Action, claim 6 has been rejected under 35 U.S.C. §102(b) for being anticipated by Japanese Laid Open Patent No. 11-3048 ("JP 11-3048"). This rejection is respectfully traversed.

Claim 6 of the present Application recites an organic EL device, comprising: ... a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT with a conductive interface pad connected thereto, a capacitor formed on the first insulating substrate and a conductive bump pad formed on the conductive interface pad.

JP 11-3048 neither discloses nor suggests such features. The Examiner alleges that JP 11-3048 discloses conductive interface pad 22, referring to Figs. 1-7. However, numeral 22 of

the Fig. 7 in JP 11-3048 is nothing but a drain electrode. It is patentably different from the conductive interface pad recited in claim 6 of the present Application. Therefore, claim 6 is patentable over JP 11-3048.

Likewise, claims 7-8, and 25 that are dependent from claim 6 are also patentable over JP 11-3048.

The Examiner rejected claims 6-8 and 25 again under 35 U.S.C. §102(b) for being anticipated by Japanese Laid Open Patent No. 11-8065 ("JP 11-8065"). This rejection is respectfully traversed.

As discussed previously, claim 6 of the present Application discloses an organic EL device, comprising: ... a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT with a conductive interface pad connected thereto, a capacitor formed on the first insulating substrate and a conductive bump pad formed on the conductive interface pad.

JP 11-8065 also fails to disclose or suggest such features. As discussed above, JP 11-8065 does not disclose a conductive interface pad connected to the TFT. Therefore, claims 6 is also patentable over JP 11-8065.

For the same reason, claims 7-8 and 25 that are dependent from claim 6 are also patentable over JP 11-8065.

Accordingly, Applicants respectfully request that the rejection over claims 6-8 and 25 be withdrawn.

Other Matters

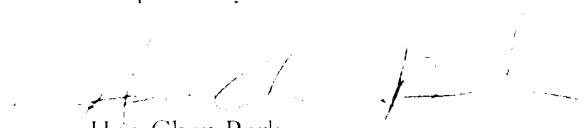
On page 5 of the Office Action, the Examiner allowed claims 9-11. Applicants appreciate for the allowance.

CONCLUSION

All of the stated grounds of objection and rejection have been properly traversed, accommodated, or rendered moot. Applicants therefore respectfully request that the Examiner reconsider all presently outstanding objections and rejections and that they be withdrawn. Applicants believe that a full and complete response has been made to the outstanding Office Action and, as such, claims 1, 3-12 and 25 are in condition for allowance or, in the alternative, in a better form for appeal. If the Examiner believes, for any reason, that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at the number provided.

Prompt and favorable consideration of this Amendment is respectfully requested.

Respectfully submitted,



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APPENDIX A

1. (Previously Amended) An organic EL device, comprising:
a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT with a conductive interface pad connected thereto and a capacitor formed on the first insulating substrate; and
an organic EL substrate including a second insulating substrate, a transparent electrode, an organic EL layer and a metal electrode,
wherein the conductive interface pad is directly connected to the metal electrode.
3. (Presiously Amended) The device of claim 1, wherein the organic EL substrate further includes a protection film that prevents external oxygen and moisture from permeating.
4. The device of claim 3, wherein the protection film is formed by depositing a SiNx layer and a SiO₂ layer at least once.
5. The device of claim 4, wherein the TFT array substrate and the organic EL substate are sealed by a UV-curable agent.
6. (Previously Amended) An organic EL device, comprising:
a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT with a conductive interface pad connected thereto, a capacitor formed on the first insulating substrate and a conductive bump pad formed on the conductive interface pad; and

an organic EL substrate including a second insulating substrate, a transparent electrode,
an organic EL layer and a metal electrode,

wherein the conductive bump pad is directly connected to the metal electrode.

7. (Previously Amended) The organic EL device of claim 25, wherein the conductive bonding agent is an anisotropic conductive film (ACF).

8. (Previously Amended) The organic EL device of claim 7, wherein the anisotropic conductive film prevents external oxygen and moisture.

9. (Previously Amended) An organic EL device, comprising:
a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT, a capacitor formed on the first insulating substrate, a conductive interface pad and a conductive bump pad formed on the conductive interface pad; and

an organic EL substrate including a second insulating substrate, a transparent electrode,
an organic EL layer and a metal electrode, and a polymer bump,

wherein the conductive bump pad contacts a portion of the metal electrode corresponding to the polymer bump by a conductive bonding agent, and

wherein the TFT is electrically connected to the metal electrode.

10. The device of claim 9, wherein the conductive bonding agent is an anisotropic conductive film (ACF).

11. (Previously Amended) The device of claim 10, wherein the anisotropic conductive film prevents oxygen and moisture from permeating through the second insulating substrate.

12. The device of claim 1, wherein the transparent electrode, the organic EL layer and the metal electrode are sequentially stacked on the second insulating layer.

25. (Previously Added) The organic EL device of claim 6, wherein the conductive bump pad is directly connected to the metal electrode with a conductive bonding agent.